



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPTG018N08NM5	<b>Issued</b>	18. August 2021
<b>MA#</b>	MA005432044		
<b>Package</b>	PG-HSOG-8-1	<b>Weight*</b>	705.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.510	0.64	0.64	6395	6395
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.03	19.06	190346	190594
wire	non noble metal	aluminium	7429-90-5	15.578	2.21	2.21	22092	22092
encapsulation	inorganic material	zinc oxide	1314-13-2	2.622	0.37		3718	
	miscellaneous	miscellaneous	-	10.488	1.49		14873	
	plastics	epoxy resin	-	39.328	5.58		55774	
	inorganic material	silicon dioxide	60676-86-0	209.751	29.75	37.19	297464	371829
lead finish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11784	11784
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	311	312
solder	non noble metal	tin	7440-31-5	0.077	0.01		110	
	noble metal	silver	7440-22-4	0.097	0.01		137	
	non noble metal	lead	7439-92-1	3.695	0.52	0.54	5241	5488
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		392	
	non noble metal	copper	7440-50-8	275.705	39.10	39.15	390997	391506
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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